

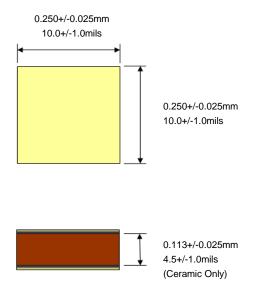
TECDIA CO., LTD.

2F Tamachi Kiyota Bldg.

4-3-4 Shibaura Minato-ku, Tokyo 108-0023 Japan

TEL: 81-3-5765-5400 FAX: 81-3-5765-5404

SPECIFICATION SHEET



Manufactured to metric dimensions. Imperial units are for reference only.

Mandidetared to metro dimensione. Imperial dritte are for reference only.					
CMS0R4B1BC					
90					
0.4[pF] @ 1MHz, 1 Vrms, 25°C, No DC Bias					
B (tolerance: +/- 0.10pF)					
0.25% Max @ 1MHz, 1 Vrms, 25°C, No DC Bias					
50 V					
1,000,000MΩ Min @ 50Vdc, 25°C					
No breakdown @ 125Vdc x 2sec, 25°C					
-330 \pm 60 ppm/°C (S2H @ -55°C to +125°C)@ No DC Bias					
TiW-Pt - Au 2.5µm Min					
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NOTES:

- Other specifications not listed are available at www.tecdia.com.
 Specifications may be subject to change without prior notice.
- · RoHS compliant.
- Wire bonding location should be 25um or further from edges of the electrode to avoid electrode peeling.
- Capacitance, Temperature Coefficient and Dissipation Factor are measured before any AC or DC bias has been applied.
- Recommended Storage Conditions (Waffle Packaging): 23 +/- 10°C @ 60% RH Max
- Guaranteed Shelf Life: 1 year after delivery under recommended storage conditions.
- Successful wire bonding and die attachment are dependent on the types of bonding tools and conditions used. Please check the wire bonding and die attach conditions of your site to prevent the wire/electrode from peeling or detaching.

Tecdia is not responsible for mechanical issues such as cracking or detaching that can occur when solder die mounting.

PREPARED BY:		DESCRIPTION:				
M. Simpson	2020/1/14	CHIP CAPACITOR	Scale:	Not to	o Scale	Э
APPROVED BY:		TECDIA PART NUMBER:	SHEET:			
T. Yoshikawa	2020/1/14	CMS0R4B1BC	1	of	1	